

# Electro-Magnetic Buzzer (SMD type)

- 2-4 HCS1205C5-7 HCS0903H
- 8-10 HCS0905H



# HCS1205C

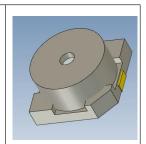
#### **Electro-Magnetic Buzzer**

# 1. Product type: Electro-Magnetic Buzzer (SMD Type)

# 2. Technical Parameter

Measuring condition

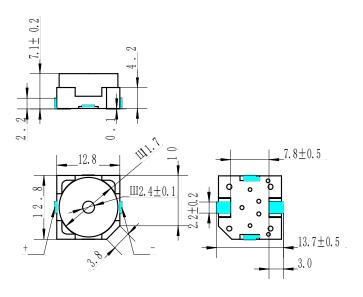
Part shall be measured under a condition (Temperature:  $5 \sim 35^{\circ}$ C, Humidity:  $45\% \sim 85\%$ R.H., Atmospheric pressure:  $860 \sim 1060$ hPa) unless the standard condition (Temperature:  $25\pm3^{\circ}$ C, Humidity:  $60\pm10\%$ R.H. Atmospheric pressure:  $860 \sim 1060$ hPa) is regulated to measure.



1	Rated Voltage	5Vо-р		
2	Operating Voltage	3 ~ 8Vo-p		
3	Rated Current	Max.160mA ,at 2400Hz 50% duty Squ	are Wave 5Vo-p	
4	Sound Output at 10cm	Min. 85dB,at 2400Hz 50% duty Square	e Wave 5Vo-p	
5	Coil Resistance	8±1 <b>Ω</b>		
6	Resonant Frequency	2400Hz		
7	Operating Temperature	<b>-40℃ ,+85°</b> C		
8	Store Temperature	-40℃ ,+85℃		
9	Net Weight	Approx 1.8g		
10	RoHS	Yes		

#### 3. Dimensions





\*Unit: mm; Tolerance:  $\pm$ 0.3mm Except Specified \*Housing Material: Black LCP \*Terminal plate: 2 soldering pads, tin Plating Brass

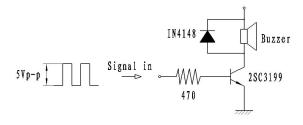


# HCS1205C

**Electro-Magnetic Buzzer** 

# 4. Electrical And Acoustical Measuring Condition

#### **Recommended Driving Circuit**

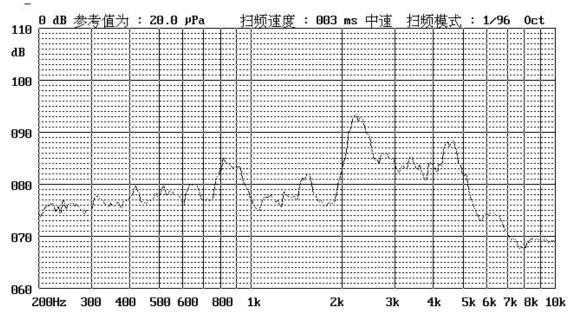


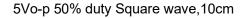
Resonant frequency, 1/2 duty cycle. Square wave. Signal amplitude should be large enough tosaturate the transistor.

#### SM -1641 FUNCTION GENERATOR **信号发生仪** Amplifier Buzzer U Buzzer Buzzer Buzzer U Buzzer Buze

**Recommended Setting** 

# 5. Frequency Response





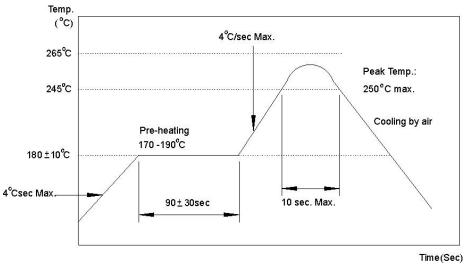


**Electro-Magnetic Buzzer** 

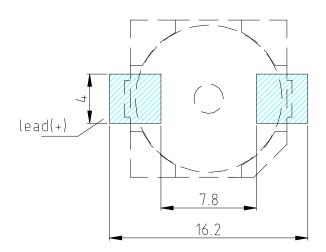
#### 6.Surface mounting condition

6.1 Reflow soldering

Recommendable reflow soldering condition is as follows.



- Note: (1) In automated mounting of the SMD sound transducers on PCB, any bending, expanding and pulling forces or shocks against the SMD sound transducers shall be kept minimum to prevent them from electrical failures and mechanical damages of the devices.
  (2) In the reflow soldering, too high soldering temperatures and too large temperature Gradient such as rapid heating or cooling may cause electrical failures and mechanical damages of the devices.
  - 6.2 Soldering pattern





# HCS0903H

# Electro-Magnetic Buzzer

# 1. Product type: Electro-Magnetic Buzzer (SMD Type)

# 2. Technical Parameter

#### Measuring condition

Part shall be measured under a condition (Temperature:  $5 \sim 35^{\circ}$ C, Humidity:  $45\% \sim 85\%$ R.H., Atmospheric pressure:  $860 \sim 1060$ hPa) unless the standard condition (Temperature:  $25\pm3^{\circ}$ C, Humidity:  $60\pm10\%$ R.H. Atmospheric pressure:  $860 \sim 1060$ hPa) is regulated to measure.

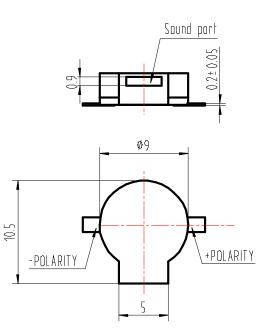


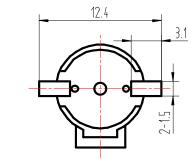
measure.					
1	Rated Voltage	ЗVо-р			
2	Operating Voltage	2 ~ 4Vo-p			
3	Rated Current	Max.80mA ,at 2730Hz 50% duty Square Wave 3Vo-p			
4	Sound Output at 10cm	Min. 90dB,at 2730Hz 50% duty Square Wave 3Vo-p			
5	Coil Resistance	16±3Ω			
6	Resonant Frequency	2730Hz			
7	Operating Temperature	<b>-20℃ ,+70</b> ℃			
8	Store Temperature	<b>-40℃ ,+85</b> ℃			
9	Net Weight	Approx 0.4g			
10	RoHS	Yes			

4.0



Unit: mm





\*Unit: mm; Tolerance:  $\pm$ 0.3mm Except Specified \*Housing Material: Black LCP \*Terminal plate: 2 soldering pads, tin Plating Brass



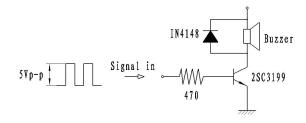
# HCS0903H

**Electro-Magnetic Buzzer** 

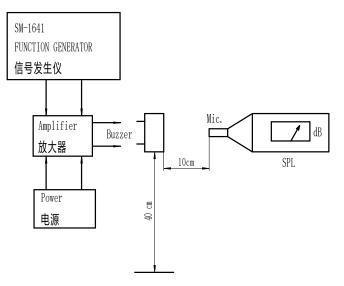
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#### **Recommended Driving Circuit**

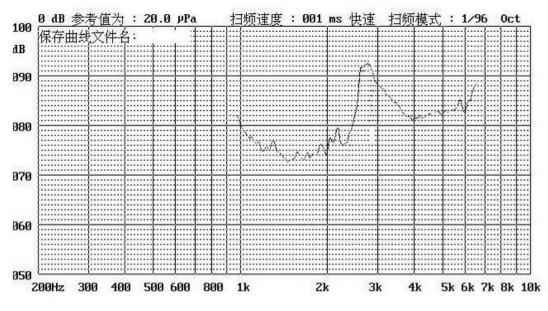


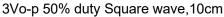


Resonant frequency, 1/2 duty cycle. Square wave. Signal amplitude should be large enough tosaturate the transistor.



# 5. Frequency Response





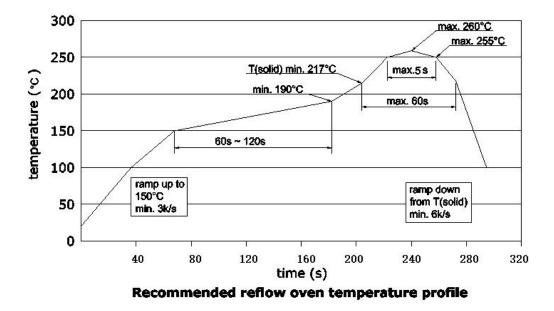


# **Electro-Magnetic Buzzer**

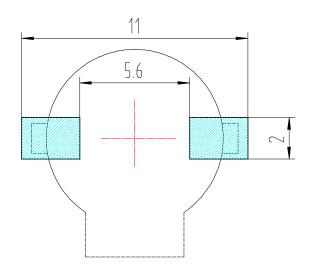
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  - 6.2 Soldering pattern





# HCS0905H

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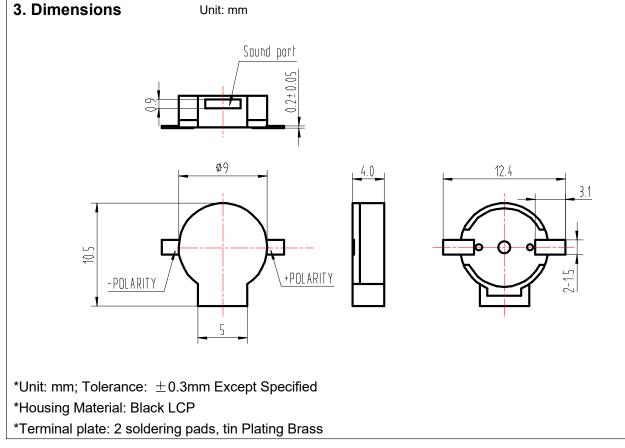
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	measure.		
1	Rated Voltage	5Vo-p	
2	Operating Voltage	4 ~ 6Vo-p	
3	Rated Current	Max.80mA ,at 2730Hz 50% duty Square Wave 5Vo-p	
4	Sound Output at 10cm	Min. 90dB,at 2730Hz 50% duty Square Wave 5Vo-p	
5	Coil Resistance	30±3Ω	
6	Resonant Frequency	2730Hz	
7	Operating Temperature	-20°C .+70°C	
8	Store Temperature	-40℃ +85℃	
9	Net Weight	Approx 0.4g	
10	RoHS	Yes	
	•		



# HCS0903H

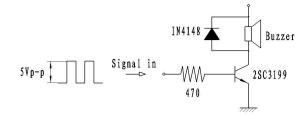
**Electro-Magnetic Buzzer** 



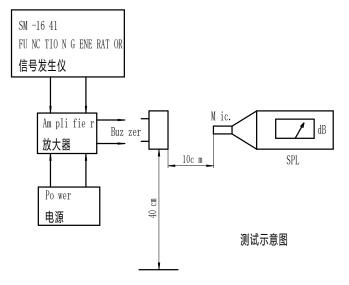
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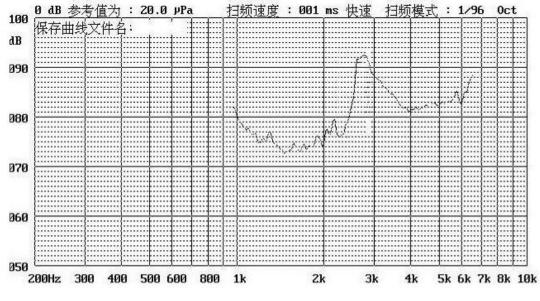




Resonant frequency, 1/2 duty cycle. Square wave. Signal amplitude should be large enough tosaturate the transistor.



# 5. Frequency Response





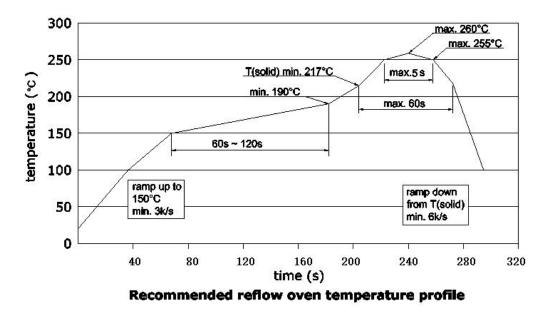


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